

Professional High Temperature Thin Film MELF Resistors



FEATURES

- 175 °C specified operating temperature
- IECQ-CECC approved according to EN 140401-803
- AEC-Q200 qualified
- Advanced metal film technology
- Excellent stability < 0.1 %
- Intrinsic sulfur resistance
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT

HALOGEN
FREE
GREEN
(5-2008)

MMA 0204 professional high temperature MELF resistors are the perfect choice for most fields of modern professional electronics where high operating temperatures, power rating, reliability and stability is of major concern. These improved properties are enabled by a modified resistive film material. The typical applications in the fields of automotive and industrial equipment reflect the outstanding level of proven reliability.

APPLICATIONS

- Automotive
- Industrial

TECHNICAL SPECIFICATIONS	
DESCRIPTION	MMA 0204 HT
DIN size	0204
Metric size code	RC3715M
Resistance range	47 Ω to 100 k Ω ; 0 Ω
Resistance tolerance	$\pm 1 \%$; $\pm 0.5 \%$
Temperature coefficient	± 50 ppm/K; ± 25 ppm/K
Rated dissipation, $P_{70}^{(1)}$	0.5 W
Operating voltage, U_{max} AC/RMS/DC	200 V
Permissible film temperature, $\vartheta_{F max}^{(1)}$	175 °C
Operating temperature range $^{(1)}$	-55 °C to 175 °C
Permissible voltage against ambient (insulation): 1 min, U_{ins}	300 V
Failure rate: FIT _{observed}	$\leq 0.05 \times 10^{-9}/h$

Note

⁽¹⁾ Please refer to APPLICATION INFORMATION below

APPLICATION INFORMATION

When the resistor dissipates power, a temperature rise above the ambient temperature occurs, dependent on the thermal resistance of the assembled resistor together with the printed circuit board. The rated dissipation applies only if the permitted film temperature is not exceeded.

These resistors do not feature a limited lifetime when operated within the permissible limits. However, resistance value drift increasing over operating time may result in exceeding a limit acceptable to the specific application, thereby establishing a functional lifetime.



MAXIMUM RESISTANCE CHANGE AT RATED DISSIPATION				
OPERATION MODE		STANDARD	POWER	HIGH TEMPERATURE
Rated dissipation, P_{70}	MMA 0204 HT	0.25 W	0.4 W	0.5 W
Operating temperature range		-55 °C to 125 °C	-55 °C to 155 °C	-55 °C to 175 °C
Permissible film temperature, ϑ_f max.		125 °C	155 °C	175 °C
		MMA 0204 HT 47 Ω to 100 k Ω		
Max. resistance change at P_{70} for resistance range, $ \Delta R/R $ after:		1000 h	$\leq 0.10 \%$	$\leq 0.15 \%$
		8000 h	$\leq 0.15 \%$	$\leq 0.35 \%$
		225 000 h	$\leq 1.0 \%$	-

Note

- The presented operation modes do not refer to different types of resistors, but actually show examples of different loads, that lead to different film temperatures and different achievable load-life stability (drift) of the resistance value. A suitable low thermal resistance of the circuit board assembly must be safeguarded in order to maintain the film temperature of the resistors within the specified limits. Please consider the application note "Thermal Management in Surface-Mounted Resistor Applications" (www.vishay.com/doc?28844) for information on the general nature of thermal resistance

TEMPERATURE COEFFICIENT AND RESISTANCE RANGE (1)				
TYPE / SIZE	TCR	TOLERANCE	RESISTANCE	E-SERIES
MMA 0204 HT	± 50 ppm/K	$\pm 1 \%$	47 Ω to 100 kΩ	E24; E96
		$\pm 0.5 \%$	47 Ω to 100 k Ω	E24; E192
	± 25 ppm/K	$\pm 1 \%$	47 Ω to 100 k Ω	E24; E96
		$\pm 0.5 \%$	47 Ω to 100 kΩ	E24; E192
	Jumper (2); $I_{max.} = 3$ A	≤ 10 m Ω	0 Ω	-

Notes

- Resistance ranges printed in bold are preferred TCR / tolerance combinations
- (1) For the approved IECQ-CECC resistance range, please refer to www.vishay.com/doc?28945
- (2) The temperature coefficient of resistance (TCR) is not specified for 0 Ω jumpers

PACKAGING						
TYPE / SIZE	CODE	QUANTITY	PACKAGING STYLE	WIDTH	PITCH	PACKAGING DIMENSIONS
MMA 0204 HT	B3 = BL	3000	Antistatic blister tape acc. IEC 60286-3, Type 2a	8 mm	4 mm	$\varnothing$ 180 mm / 7"
	B0	10 000				$\varnothing$ 330 mm / 13"

**PART NUMBER AND PRODUCT DESCRIPTION**

Part Number: MMA0204TD5620DB300

Part Number: MMA0204TZ0000ZB300

M	M	A	0	2	0	4	T	D	5	6	2	0	D	B	3	0	0
M	M	A	0	2	0	4	T	Z	0	0	0	0	Z	B	3	0	0

TYPE / SIZE
MMA0204

VERSION
T = HT

TCR
D = ± 25 ppm/K
C = ± 50 ppm/K
Z = jumper

RESISTANCE
3 digit value
1 digit multiplier
Multiplier
9 = $\times 10^{-1}$
0 = $\times 10^0$
1 = $\times 10^1$
2 = $\times 10^2$
3 = $\times 10^3$
0000 = jumper

TOLERANCE
D = ± 0.5 %
F = ± 1 %
Z = jumper

PACKAGING
B3
B0

Product Description: MMA 0204 - 25 0.5 % HT BL 562R

Product Description: MMA 0204 HT BL 0R0

MMA	0204	- 25	0.5 %	HT	BL	562R
MMA	0204	-	-	HT	BL	0R0
TYPE	SIZE	TCR	TOLERANCE	VERSION	PACKAGING	RESISTANCE
MMA	0204	± 25 ppm/K ± 50 ppm/K	± 0.5 % ± 1 %	HT = high temperature	BL B0	562R = 562 Ω 0R0 = jumper

Note

- Products can be ordered using either the PART NUMBER or the PRODUCT DESCRIPTION



DESCRIPTION

Production is strictly controlled and follows an extensive set of instructions established for reproducibility. A homogeneous film of metal alloy is deposited on a high grade ceramic body (Al_2O_3) and conditioned to achieve the desired temperature coefficient. Nickel plated steel termination caps are firmly pressed on the metallised rods. A special laser is used to achieve the target value by smoothly cutting a helical groove in the resistive layer without damaging the ceramics. The resistor elements are covered by a protective coating designed for electrical, mechanical and climatic protection. The terminations receive a final pure matte tin on nickel plating. Four or five color code rings designate the resistance value and tolerance in accordance with **IEC 60062** ⁽¹⁾.

The result of the determined production is verified by an extensive testing procedure performed on 100 % of the individual resistors. This includes pulse load screening and additional non-linearity screening for the elimination of products with a potential risk of early life failures according to EN 140401-803, 2.1.2.2. Only accepted products are laid directly into the blister tape in accordance with **IEC 60286-3, Type 2a** ⁽¹⁾ or bulk case in accordance with **IEC 60286-6** ⁽²⁾.

ASSEMBLY

The resistors are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering using wave, reflow or vapor phase as shown in **IEC 61760-1** ⁽¹⁾. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters and aqueous solutions. The suitability of conformal coatings, potting compounds and their processes, if applied, shall be qualified by appropriate means to ensure the long term stability of the whole system.

The resistors are completely lead (Pb)-free, the pure matte tin plating provides compatibility with lead (Pb)-free and lead containing soldering processes. Solderability is specified for 2 years after production or requalification, however, excellent solderability is proven after extended storage in excess of 10 years. The permitted storage time is 20 years. The immunity of the plating against tin whisker growth has been proven under extensive testing.

MATERIALS

Vishay acknowledges the following systems for the regulation of hazardous substances:

- IEC 62474, Material Declaration for Products of and for the Electrotechnical Industry, with the list of declarable substances given therein ⁽²⁾
- The Global Automotive Declarable Substance List (GADSL) ⁽³⁾
- The REACH regulation (1907/2006/EC) and the related list of substances with very high concern (SVHC) ⁽⁴⁾ for its supply chain

Notes

- ⁽¹⁾ The quoted IEC standards are also released as EN standards with the same number and identical contents
- ⁽²⁾ The IEC 62474 list of declarable substances is maintained in a dedicated database, which is available at <http://std.iec.ch/iec62474>
- ⁽³⁾ The Global Automotive Declarable Substance List (GADSL) is maintained by the American Chemistry Council and available at www.gadsl.org
- ⁽⁴⁾ The SVHC list is maintained by the European Chemical Agency (ECHA) and available at <http://echa.europa.eu/candidate-list-table>

The products do not contain any of the banned substances as per IEC 62474, GADSL, or the SVHC list, see www.vishay.com/how/leadfree.

Hence the products fully comply with the following directives:

- 2000/53/EC End-of-Life Vehicle Directive (ELV) and Annex II (ELV II)
- 2011/65/EU Restriction of the Use of Hazardous Substances Directive (RoHS) with amendment 2015/863/EU
- 2012/19/EU Waste Electrical and Electronic Equipment Directive (WEEE)

Vishay pursues the elimination of conflict minerals from its supply chain, see the Conflict Minerals Policy at www.vishay.com/doc?49037.

APPROVALS

Where applicable, the resistors are approved within the IECQ-CECC Quality Assessment System for Electronic Components to the detail specification **EN 140401-803** which refers to **EN 60115-1**, **EN 60115-8** and the variety of environmental test procedures of the **IEC 60068** ⁽¹⁾ series.

Conformity is attested by the use of the **CECC** logo () as the mark of conformity on the package label.

Vishay Beyschlag has achieved “**Approval of Manufacture**” in accordance with **IECQ 03-1**. The release certificate for “**Technology Approval Schedule**” in accordance with **CECC 240001** based on **IECQ 03-3-1** is granted for the Vishay Beyschlag manufacturing process. The resistors are qualified according to AEC-Q200.

RELATED PRODUCTS

A wider range of TCR, tolerance and resistance values, plus the option of values from a different E series is available with products approved to **EN 140401-803**, Version A, without established reliability, nominal failure rate level E0 (Quality factor $\pi_Q = 3$). See the datasheets:

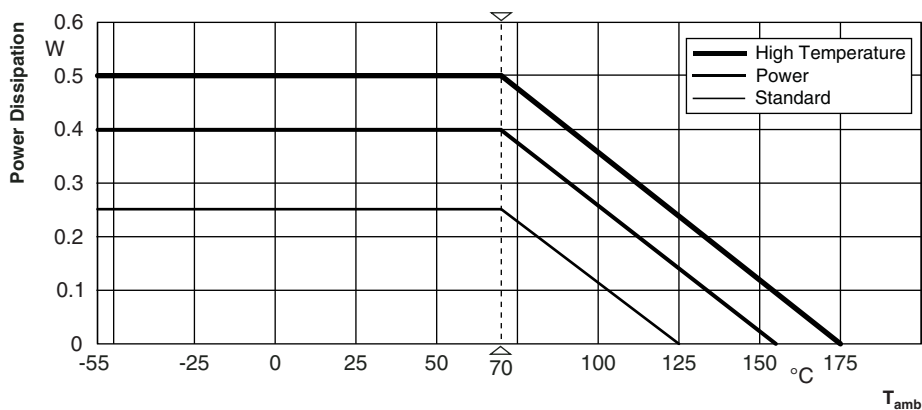
- “Professional MELF Resistors”
(www.vishay.com/doc?28713)
- “Precision MELF Resistors”
(www.vishay.com/doc?28714)
- “High Precision MELF Resistor”
(www.vishay.com/doc?28715)

For products with superior pulse load capability, see the datasheets:

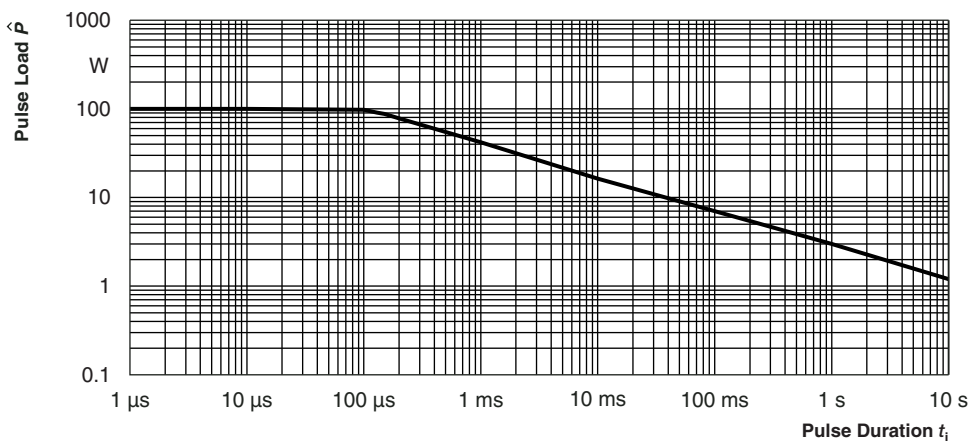
- “High Pulse Load Carbon Film MINI-MELF Resistor”
(www.vishay.com/doc?28717)
- “High Pulse Load Carbon Film MELF Resistor”
(www.vishay.com/doc?28755)



FUNCTIONAL PERFORMANCE

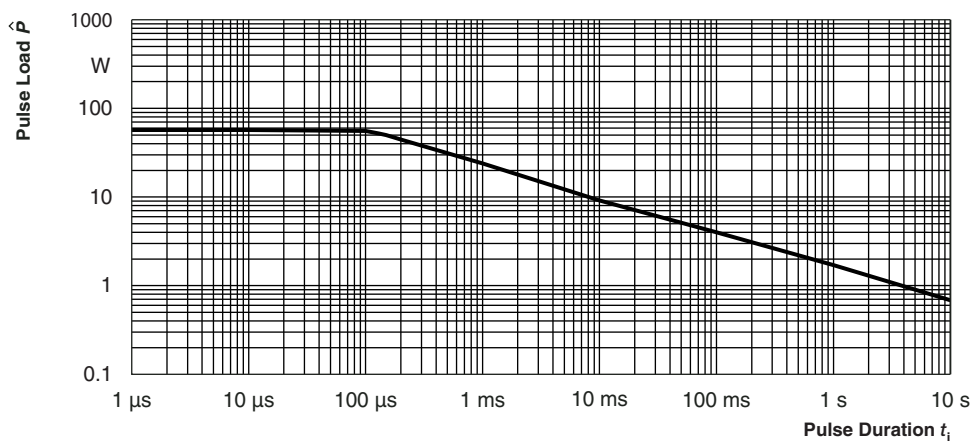


Derating for Operation Modes



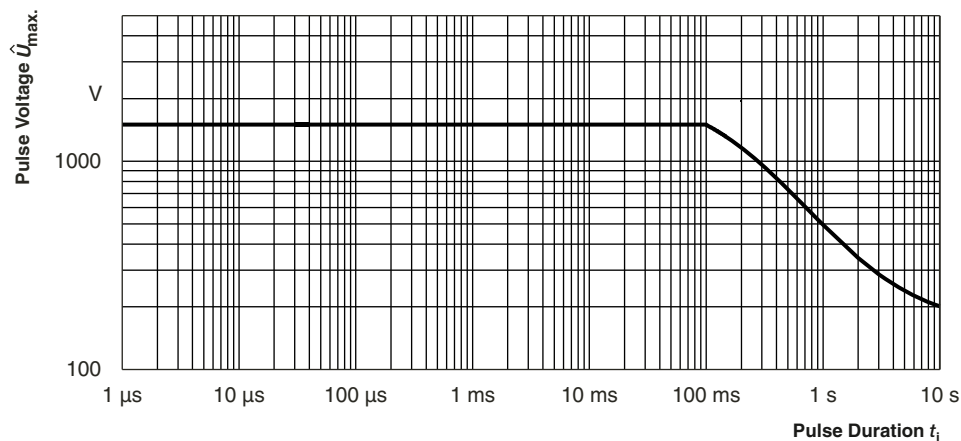
Maximum pulse load, single pulse; applicable if $\bar{P} \rightarrow 0$ and $n \leq 1000$ and $\hat{U} \leq \hat{U}_{max}$; for permissible resistance change $\pm (0.5 \% R + 0.01 \Omega)$

Single Pulse



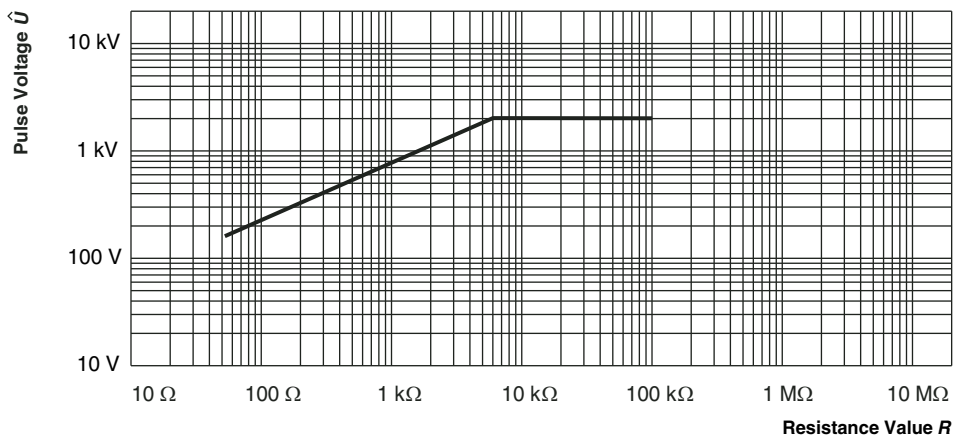
Maximum pulse load, continuous pulse; applicable if $\bar{P} \leq P(\vartheta_{amb})$ and $\hat{U} \leq \hat{U}_{max}$; for permissible resistance change $\pm (0.5 \% R + 0.01 \Omega)$

Continuous Pulse



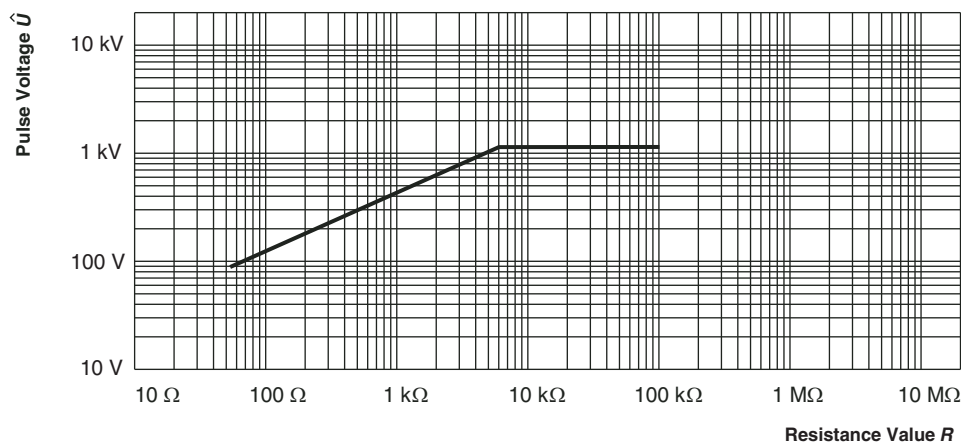
Maximum pulse voltage, single and continuous pulses; applicable if $\hat{P} \leq \hat{P}_{max}$; for permissible resistance change $\pm (0.5 \% R + 0.01 \Omega)$

Pulse Voltage



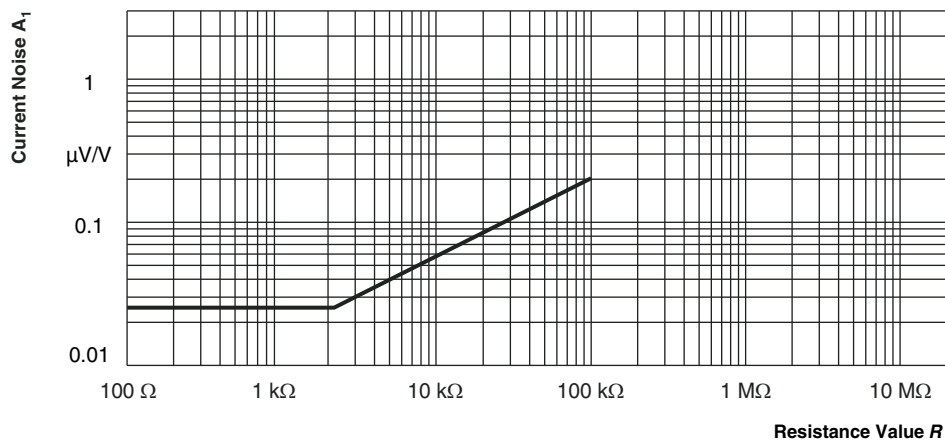
Pulse load rating in accordance with IEC 60115-1, 4.27; 1.2 μ s/50 μ s;
5 pulses at 12 s intervals; for permissible resistance change 0.5 %

1.2/50 Pulse



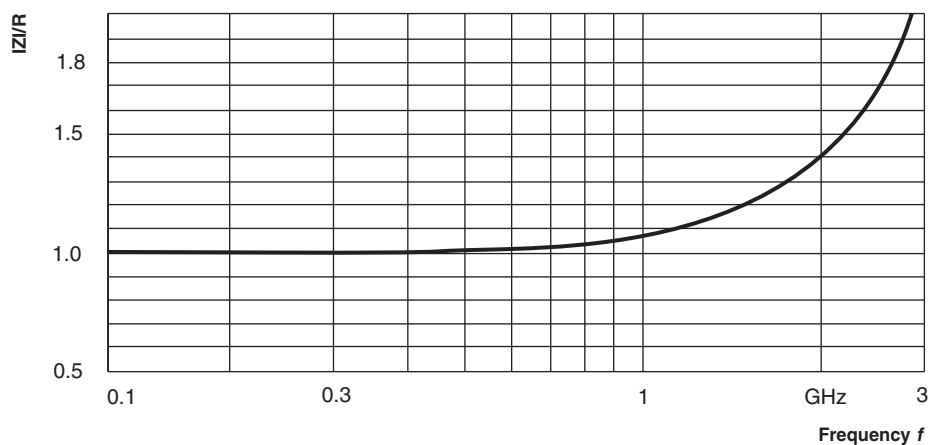
Pulse load rating in accordance with IEC 60115-1, 4.27; 10 μ s/700 μ s;
10 pulses at 1 min intervals; for permissible resistance change 0.5 %

10/700 Pulse



In accordance with IEC 60195

Current Noise - A_1



$|Z|/R$ for 49.9 Ω MELF resistors

RF - Behaviour

TESTS AND REQUIREMENTS

All tests are carried out in accordance with the following specifications:

EN 60115-1, generic specification

EN 60115-8 (successor of EN 140400), sectional specification

EN 140401-803, detail specification

IEC 60068-2-xx, test methods

The components are approved under the IECQ-CECC quality assessment system for electronic components.

The parameters stated in the Test Procedures and Requirements table are based on the required tests and permitted limits of EN 140401-803. The table presents only the most important tests, for the full test schedule refer to the documents listed above. However, some additional tests and a number of improvements against those minimum requirements have been included.

The testing also covers most of the requirements specified by EIA/ECA-703 and JIS-C-5201-1.

The tests are carried out under standard atmospheric conditions in accordance with IEC 60068-1, 4.3, whereupon the following values are applied:

Temperature: 15 $^{\circ}C$ to 35 $^{\circ}C$

Relative humidity: 25 % to 75 %

Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar)

A climatic category LCT / UCT / 56 is applied, defined by the lower category temperature (LCT), the upper category temperature (UCT), and the duration of exposure in the damp heat, steady state test (56 days).

The components are mounted for testing on printed circuit boards in accordance with EN 60115-8, 2.4.2, unless otherwise specified.



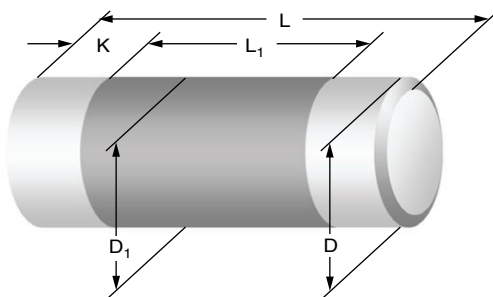
TEST PROCEDURES AND REQUIREMENTS				
EN 60115-1 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR)
				STABILITY CLASS 0.25 OR BETTER
			Stability for product types:	
			MMA 0204 HT	47 Ω to 100 KΩ
4.5	-	Resistance	-	± 1 % R; ± 0.5 % R
4.8	-	Temperature coefficient	At (20/-55/20) °C and (20/155/20) °C	± 50 ppm/K; ± 25 ppm/K
4.25.1	-	Endurance at 70 °C: Standard operation mode	$U = \sqrt{P_{70} \times R}$ or $U = U_{max.}$; whichever is the less severe; 1.5 h on; 0.5 h off; 70 °C; 1000 h 70 °C; 8000 h	± (0.10 % R + 10 mΩ) ± (0.15 % R + 10 mΩ)
		Endurance at 70 °C: Power operation mode	$U = \sqrt{P_{70} \times R}$ or $U = U_{max.}$; whichever is the less severe; 1.5 h on; 0.5 h off; 70 °C; 1000 h 70 °C; 8000 h	± (0.15 % R + 10 mΩ) ± (0.35 % R + 10 mΩ)
		Endurance at 70 °C: High temperature mode	$U = \sqrt{P_{70} \times R}$ or $U = U_{max.}$; whichever is the less severe; 1.5 h on; 0.5 h off; 70 °C; 1000 h	± (0.25 % R + 10 mΩ)
4.25.3	-	Endurance at upper category temperature	125 °C; 1000 h	± (0.05 % R + 5 mΩ)
			155 °C; 1000 h	± (0.15 % R + 5 mΩ)
			175 °C; 1000 h	± (0.25 % R + 5 mΩ)
4.24	78 (Cab)	Damp heat, steady state (standard mode)	(40 ± 2) °C; 56 days; (93 ± 3) % RH	± (0.15 % R + 10 mΩ)
4.37	67 (Cy)	Damp heat, steady state, accelerated (standard mode)	(85 ± 2) °C; (85 ± 5) % RH; $U = 0.3 \times \sqrt{P_{70} \times R} \leq 100 \text{ V}$ and $U = 0.3 \times U_{max.}$; (the smaller value is valid) 1000 h	± (0.25 % R + 10 mΩ)
4.23	2 (Bb) 30 (Db) 1 (Ab) 13 (M) 30 (Db) -	Climatic sequence:		
4.23.2		Dry heat	UCT; 16 h 55 °C; 24 h; ≥ 90 % RH; 1 cycle	
4.23.3		Damp heat, cyclic	LCT; 2 h	
4.23.4		Cold	8.5 kPa; 2 h; (25 ± 10) °C	
4.23.5		Low air pressure	55 °C; 24 h; ≥ 90 % RH; 5 cycles	± (0.15 % R + 10 mΩ)
4.23.6		Damp heat, cyclic	$U = \sqrt{P_{70} \times R} \leq U_{max.}$; 1 min LCT = - 55 °C; UCT = 155 °C	
4.23.7		DC load (High temperature mode)		
-	1 (Ab)	Cold	-55 °C; 2 h	± (0.05 % R + 5mΩ)
4.19	14 (Na)	Rapid change of temperature	30 min at LCT; 30 min at UCT; LCT = -55 °C; UCT = 125 °C 5 cycles 1000 cycles	± (0.05 % R + 10 mΩ) ±(0.15 % R + 10 mΩ)
			LCT = -55 °C; UCT = 155 °C 1000 cycles	±(0.25 % R + 10 mΩ)

TEST PROCEDURES AND REQUIREMENTS				
EN 60115-1 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR)
			Stability for product types:	
			MMA 0204 HT	47 Ω to 100 K Ω
4.13	-	Short time overload; Standard operation mode	$U = 2.5 \times \sqrt{P_{70} \times R}$ or $U = 2 \times U_{max.}$; whichever is the less severe; 5 s	$\pm(0.03 \% R + 5 \text{ m}\Omega)$
4.27	-	Single pulse high voltage overload; Standard operation mode	Severity no. 4: $U = 10 \times \sqrt{P_{70} \times R}$ or $U = 2 \times U_{max.}$; whichever is the less severe; 10 pulses 10 μ s/700 μ s	$\pm(0.25 \% R + 5 \text{ m}\Omega)$
4.39	-	Periodic electric overload; Standard operation mode	$U = \sqrt{15 \times P_{70} \times R}$ or $U = 2 \times U_{max.}$; whichever is the less severe; 0.1 s on; 2.5 s off; 1000 cycles	$\pm(0.5 \% R + 5 \text{ m}\Omega)$
4.22	6 (Fc)	Vibration	Endurance by sweeping; 10 Hz to 2000 Hz; no resonance; amplitude $\leq 1.5 \text{ mm}$ or $\leq 200 \text{ m/s}^2$; 7.5 h	$\pm (0.05 \% R + 5 \text{ m}\Omega)$
4.38	-	Electrostatic discharge (Human Body Model)	IEC 61340-3-1*; 3 pos. + 3 neg. discharges MMA 0204 HT: 2 kV	$\pm (0.5 \% R + 50 \text{ m}\Omega)$
4.17	58 (Td)	Solderability	Solder bath method; SnPb40; non-activated flux; (215 $\pm$ 3) $^{\circ}$ C; (2 $\pm$ 0.3) s	Good tinning ($\geq 95 \%$ covered); No visible damage
			Solder bath method; SnAg3Cu0.5 or SnAg3.5; non-activated flux; (235 $\pm$ 3) $^{\circ}$ C; (2 $\pm$ 0.3) s	Good tinning ($\geq 95 \%$ covered); No visible damage
4.18	58 (Td)	Resistance to soldering heat	Solder bath method; (260 $\pm$ 5) $^{\circ}$ C; (10 $\pm$ 1) s	$\pm (0.05 \% R + 10 \text{ m}\Omega)$
			Reflow method 2 (IR/forced gas convection); (260 $\pm$ 5) $^{\circ}$ C; (40 $\pm$ 1) s (3 times)	$\pm(0.03 \% R + 10 \text{ m}\Omega)$
4.29	45 (XA)	Component solvent resistance	Isopropyl alcohol; 50 $^{\circ}$ C; method 2	No visible damage
4.30	45 (XA)	Solvent resistance of marking	Isopropyl alcohol; 50 $^{\circ}$ C; method 1, toothbrush	Marking legible; No visible damage
4.32	21 (Ue ₃)	Shear	45 N	No visible damage
4.33	21 (Ue ₁)	Substrate bending	Depth 2 mm, 3 times	No visible damage, no open circuit in bent position $\pm (0.05 \% R + 5 \text{ m}\Omega)$
4.7	-	Voltage proof	$U_{RMS} = U_{ins}$; 60 s	No flashover or breakdown
4.35	-	Flammability	IEC 60 695-11-5, needle flame test; 10 s	No burning after 30 s

Note

- The quoted IEC standards are also released as EN standards with the same number and identical contents.

DIMENSIONS

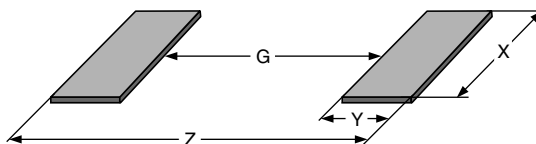


DIMENSIONS AND MASS						
TYPE / SIZE	L (mm)	D (mm)	L ₁ min. (mm)	D ₁ (mm)	K (mm)	MASS (mg)
MMA 0204 HT	3.6 + 0/- 0.2	1.4 + 0/- 0.1	1.8	D + 0/-0.15	0.75 ± 0.1	22

Note

- Color code marking is applied according to IEC 60062 ⁽¹⁾ in four bands (E24 series) or five bands (E96 or E192 series). Each color band appears as a single solid line, voids are permissible if at least $\frac{2}{3}$ of the band is visible from each radial angle of view. The last color band for tolerance is approximately 50 % wider than the other bands. An interrupted yellow band between the 4th and 5th full band indicates TC25.

PATTERN STYLES FOR MELF RESISTORS



RECOMMENDED SOLDER PAD DIMENSIONS								
TYPE / SIZE	WAVE SOLDERING				REFLOW SOLDERING			
	G (mm)	Y (mm)	X (mm)	Z (mm)	G (mm)	Y (mm)	X (mm)	Z (mm)
MMA 0204 HT	1.5	1.5	1.8	4.5	1.7	1.2	1.6	4.1

Notes

- The given solder pad dimensions reflect the considerations for board design and assembly as outlined e.g. in standards IEC 61188-5-x ⁽¹⁾, or in publication IPC-7351.

⁽¹⁾ The quoted IEC standards are also released as EN standards with the same number and identical contents.



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